



Atty. Dkt. No. 047711-0319

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajiv SHAH et al.

Title: HIGH RELIABILITY
MULTILAYER CIRCUIT
SUBSTRATES AND METHODS
FOR THEIR FORMATION

Appl. No.: 10/671,996

Filing Date: 9/26/2003

Examiner: Not assigned

Art Unit: Not assigned

<p>CERTIFICATE OF MAILING</p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, Virginia 22313-1450, on the date below.</p> <p><u>Jose Ramos</u> (Printed Name)</p> <p><u>[Signature]</u> (Signature)</p> <p><u>October 28, 2003</u> (Date of Deposit)</p>

TRANSMITTAL LETTER

Mail Stop Patent Application
Commissioner for Patents
PO Box 1450
Alexandria, Virginia 22313-1450

Sir:

Enclosed herewith is a substitute Declaration executed by Rajiv Shah indicating his new address and a new Application Data Sheet indicating the same change.

The Commissioner is hereby authorized to charge any additional fees which may be required regarding this application under 37 C.F.R. § 1.16-1.17 to Deposit Account No. 50-0872.

Respectfully submitted,

Date: October 28, 2003

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